FDI

ENGINEERING CHANGE ORDER

ECO NO: 18-005

Page 1 of 7

TITLE	CURRENT ASSY PN	CURRENT ASSY REV	NEW ASSY PN	NEW REV
uEZGUI-4357-50WVN-BA	AUG4350VNBA14	1.4	AUG4350VNBA20	2.0
uEZGUI-4357-50WVN	AUG4350VN14	1.5	AUG4350VN20	2.0

BACKGROUND:

- Update secondary expansion connector to provide QEI signal and add QEI function name to pin labels
- Update design to properly support resistive touch LCD
- Update power supply system to include dedicated USB socket for power input, change to 3A capable DCDC,
 and add input protection diode
- Add pullup to LCD 'DISP' signal to ensure the signal is pulled 'true'
- Change SD socket power supply to default power on
- Add XBee Socket no module loaded
- Add optional Security ICs and external very low power RTC
- Add optional Vertical Pmod Socket
- Add GPIO controlled reset capability for Pmod socket
- Shift MCU ADC supply filter circuit slightly away from MCU to clear the body of the MCU
- Change SDRAM to I-temp version for extended temperature support
- Update components to condense BOM common part numbers

DESCRIPTION OF CHANGE:

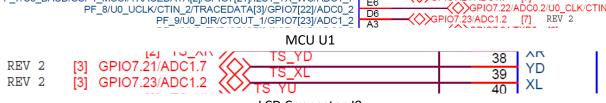
Change pin 3 of J5 from GPIO6.29/CTOUT8 to GPIO4.10/QEI_PHA



Move 4WRTP signals from ADC-only pins (U1 pin B3 & A5) to pins supporting GPIO & ADC function (U1 pin D6 & B7)

J9 pin 38 to U1 pin D6 - GPIO7.23/ADC1.2
J9 pin 39 to U1 pin B7 – GPIO7.21/ADC1.7

PF 7/U3_BAUD/SSP1_MOSI/TRACEDATA[2]/GPIO7[21]/I2S1_TX_WS/ADC1_7 E6

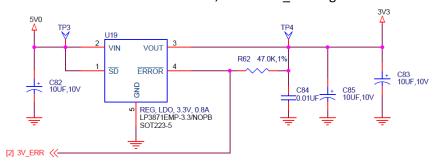


LCD Connector J9

Reason for change:			Disposition/Affectivity	
 Add support QEI F 	Add support QEI Function to expansion connectors		Use as is	х
2. Add support for re	·		Rework to ECO	
Default SD to alwa	ys on		Scrap & Rebuild	
4. Change 3.3V DCDC	and input for higher power	er support	Record Change Only	х
Add XBee Socket, 6	Optional Security ICs and E	xternal RTC	,	
6. Change SDRAM to	I temp part			
Prepared by:	MH	Date:	6/19/18	
Approved by:	TE	Date:	6/26/18	
Approved by:	CM	Date:	06/26/18	
Approved by:	KA	Date:	06/26/18	

FDI	ENGINEERING CHANGE ORDER				ge 2 of 7
TITLE	CURRENT ASSY PN	CURRENT ASSY REV	NEW ASSY PN		NEW REV
uEZGUI-4357-50WVN-BA	AUG4350VNBA14	1.4	AUG4350VNBA20		2.0
uEZGUI-4357-50WVN	AUG4350VN14	1.5	AUG4350V	N20	2.0

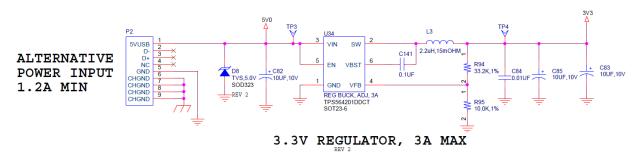
Change 3.3V DCDC from LDO to high-capacity switching DCDC IC;
 Remove U19 LP3871 U500385 and R62 47.0K R500524, delete '3V_ERR' signal



3.3V REGULATOR, 0.8A

OLD DCDC

Add U34 TPS564201 U500678, C141 C500234, L3 L500092, R94 R500748, R95 R500060, & D8 D500190



NEW DCDC

Add 5V DC input via dedicated USB Mini-B Connector, P2, FDI PN: J500027

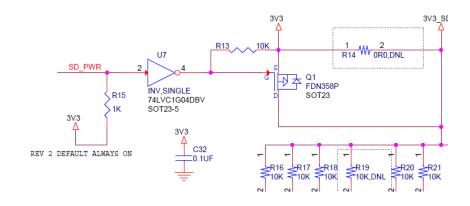
Reason for change:			Disposition/Affectivity		
 Add support QEI 	Function to expansion conr	nectors	Use as is	х	
Add support for	resistive touch LCD		Rework to ECO		
Default SD to alv	vays on		Scrap & Rebuild		
4. Change 3.3V DC	DC and input for higher pow	er support	Record Change Only	х	
Add XBee Socke	t, Optional Security ICs and E	External RTC			
6. Change SDRAM	to I temp part				
Prepared by:	MH	Date:	6/19/18		
Approved by:	TE	Date:	6/26/18		
Approved by:	CM	Date:	06/26/18		
Approved by:	KA	Date:	06/26/18		

ECO NO: 18-005 **ENGINEERING CHANGE ORDER** Page 3 of 7 TITLE **CURRENT ASSY REV NEW REV CURRENT ASSY PN NEW ASSY PN** uEZGUI-4357-50WVN-BA 2.0 AUG4350VNBA14 AUG4350VNBA20 1.4 uEZGUI-4357-50WVN AUG4350VN14 1.5 AUG4350VN20 2.0

Add 10K ohm pullup R70 R500459 to LCD DISP signal, J9 pin 31



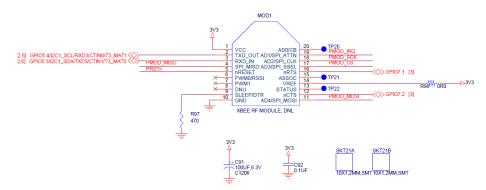
Change SD socket power switch to default to always – change R15 from pull down to pullup;



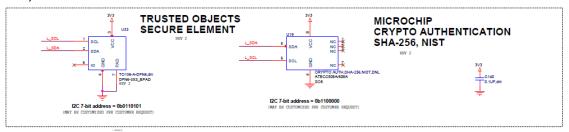
Reason for change:			Disposition/Affecti	vity
 Add support QE 	1. Add support QEI Function to expansion connectors		Use as is	х
Add support for	resistive touch LCD		Rework to ECO	
Default SD to all	vays on		Scrap & Rebuild	
4. Change 3.3V DC	DC and input for higher pow	er support	Record Change Only	х
Add XBee Socke	t, Optional Security ICs and I	External RTC	,	
6. Change SDRAM	to I temp part			
Prepared by:	МН	Date:	6/19/18	
Approved by:	TE	Date:	6/26/18	
Approved by:	CM	Date:	06/26/18	
Approved by:	KA	Date:	06/26/18	

FDI	ENGINEERING CHANGE ORDER				NO: 18-005 age 4 of 7
TITLE	CURRENT ASSY PN	CURRENT ASSY REV	NEW ASSY PN		NEW REV
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uEZGUI-4357-50WVN	AUG4350VN14	1.5	AUG4350V	N20	2.0

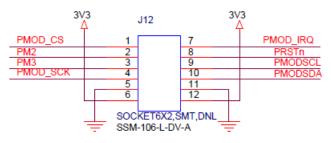
Add XBee socket for optional wireless modules, SKT21A SK50010, SKT21B SK50010, C91 C500284, C92 C500234, R97 R500469, & R96 R500436 – no module is loaded



 Add optional security ICs, U33 Trusted Objects TO136 U500691 DNL, U19 Microchip ATECC608A U500706 DNL, & C140 C500234



Add optional vertical Pmod socket, J500132 - DNL



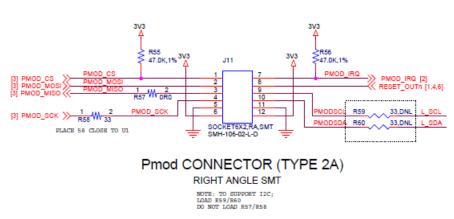
OPTIONAL STRAIGHT SMT

Reason for change:			Disposition/Affectivity	
 Add support QEI I 	Add support QEI Function to expansion connectors			х
2. Add support for r	esistive touch LCD		Rework to ECO	
3. Default SD to alw	ays on		Scrap & Rebuild	
4. Change 3.3V DCD	4. Change 3.3V DCDC and input for higher power support			х
5. Add XBee Socket, Optional Security ICs and External RTC				
6. Change SDRAM to	l temp part			
Prepared by:	MH	Date:	6/19/18	
Approved by:	TE	Date:	6/26/18	
Approved by:	CM	Date:	06/26/18	
Approved by:	KA	Date:	06/26/18	

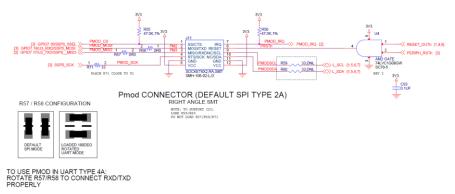
EDI				ECO N	NO: 18-005
FDI	ENGINEERING CHANGE ORDER				ge 5 of 7
TITLE	CURRENT ASSY PN	CURRENT ASSY REV	NEW ASSY PN		NEW REV
uEZGUI-4357-50WVN-BA	AUG4350VNBA14	1.4	AUG4350VN	BA20	2.0
uEZGUI-4357-50WVN	AUG4350VN14	1.5	AUG4350V	N20	2.0

Add SPI/UART zero ohm resistor configuration (on J11 pin 2 & 3) and GPIO controlled capability to generate
Peripheral Reset signal (J11 pin 8) to Pmod – connect PERIPH_RSTn to MCU U1 pin P14, GPIO7.0. In addition,
update the Pmod schematic symbol to illustrate the pin functions.

Add U4 74LVC1G08 U500382, C93 0.1uf C500234, R71 33ohm R500461 Change R58 from 33ohm R500461 to Zero ohm R500436



FROM THIS

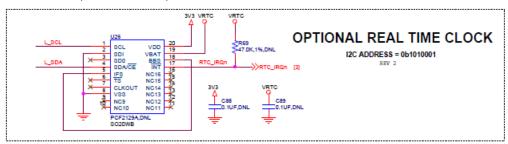


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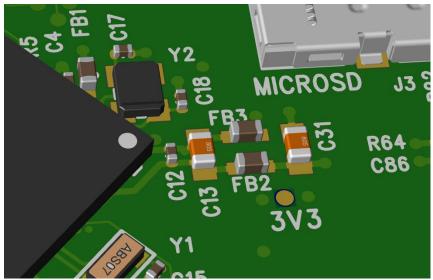
Reason for change:			Disposition/Affectivity	
 Add support QEI I 	Add support QEI Function to expansion connectors		Use as is	Х
Add support for re	esistive touch LCD		Rework to ECO	
3. Default SD to alw	ays on		Scrap & Rebuild	
4. Change 3.3V DCD	C and input for higher pow	er support	Record Change Only	х
Add XBee Socket,	Optional Security ICs and E	External RTC		
6. Change SDRAM to	o I temp part			
Prepared by:	MH	Date:	6/19/18	
Approved by:	TE	Date:	6/26/18	
Approved by:	CM	Date:	06/26/18	
Approved by:	KA	Date:	06/26/18	

ECO NO: 18-005 FDI **ENGINEERING CHANGE ORDER** Page 6 of 7 **CURRENT ASSY REV** TITLE **NEW REV CURRENT ASSY PN NEW ASSY PN** uEZGUI-4357-50WVN-BA AUG4350VNBA14 2.0 AUG4350VNBA20 1.4 uEZGUI-4357-50WVN AUG4350VN14 1.5 AUG4350VN20 2.0

 Add optional I2C Low Power, High accuracy Real Time Clock – U26 NXP PCF2125A U500438, R69 R500524, C88 C500234, C89 C500234, all DNL



 Shift MCU analog supply components (C12, C13, FB2,FB3, & C31) away from MCU to clear BGA package overhang – change C12 C500234 to LOAD



- Change SDRAM U8 from FDI PN U500654 Mfg PN: MT48LC4M32B2P-6A to FDI PN U500671 Mfg PN: IS42S32800J-6TLI ("I" Temp Part)
- Change C68 from C500252 10uf, 6.3V, 0805 to C500178 10uf, 10v, 0805 remains DNL
- Change R48 from R500127 1.5K, 5% 0603 to R500522 1.5K, 5%, 0402

Reason for change:			Disposition/Affecti	vity
 Add support QEI 	1. Add support QEI Function to expansion connectors			Х
Add support for r	esistive touch LCD		Rework to ECO	
Default SD to alw	ays on		Scrap & Rebuild	
_	4. Change 3.3V DCDC and input for higher power support		Record Change Only	Х
Add XBee Socket	, Optional Security ICs and E	xternal RTC		
6. Change SDRAM t	o I temp part			
Prepared by:	MH	Date:	6/19/18	
Approved by:	TE	Date:	6/26/18	
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ECO NO: 18-005 **FDI ENGINEERING CHANGE ORDER** Page 7 of 7 TITLE **CURRENT ASSY PN CURRENT ASSY REV NEW ASSY PN** uEZGUI-4357-50WVN-BA AUG4350VNBA14 AUG4350VNBA20 1.4

1.5

AUG4350VN14

NEW REV

2.0

2.0

AUG4350VN20

REVISION INFORMATION:

uEZGUI-4357-50WVN

	Current Rev	New Rev
uEZGUI-4357-50WVN Assembly	1.4	2.0
Sub-Assemblies		•
Mainboard Rev (AUG4350VNBA20)	1.4	2.0
Mainboard HW Signoff Rev	1.4	2.0
Schematic\BOM Rev	1	.4 2.0
PCB Rev	1	.4 2.0
Mainboard SW signoff Rev	1.1	2.0
OOB Demo	2.0	9 2.10 Beta
SD Card Image		? Videos/Slides Only
FCT Software Rev		
MainBoard FCT SW Rev	1	.1 2.0
MainBoard FCT HW Rev (increase BA Rev Only when changer affects – BA_)	1	0 1.0 (no new loopbacks)
PC FCT Application SW repository Revision	1.00	2.0

NOTE: FCT and Barcode Rev Changes ONLY increase the Overall Rev IF they result in the customer being able to see a difference in the product. In most cases these Rev changes will not result in an Overall Rev Change.

Reason for change:		_	Disposition/Affecti	vity
 Add support QEI 	Function to expansion con	nectors	Use as is	х
2. Add support for	resistive touch LCD		Rework to ECO	
Default SD to alw	<i>r</i> ays on		Scrap & Rebuild	х
4. Change 3.3V DCI	OC and input for higher pow	er support	Record Change Only	
Add XBee Socket	, Optional Security ICs and	External RTC	,	
Change SDRAM t	o I temp part			
Prepared by:	MH	Date:	6/19/18	
Approved by:	TE	Date:	6/26/18	
Approved by:	CM	Date:	06/26/18	
Approved by:	KA	Date:	06/26/18	